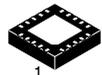


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

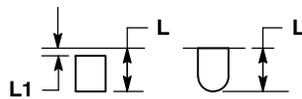
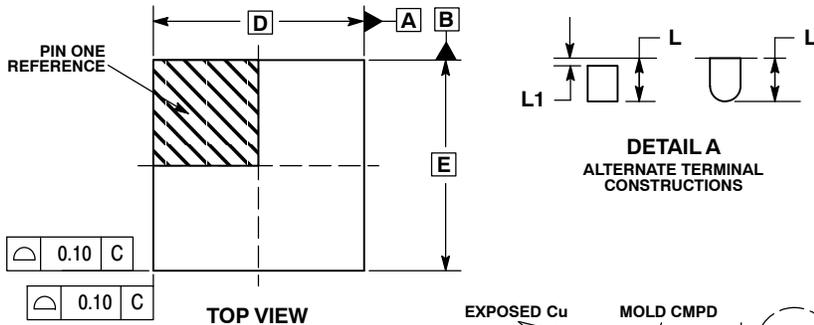


SCALE 2:1

QFN20 3.5x3.5, 0.5P

CASE 485CP
ISSUE O

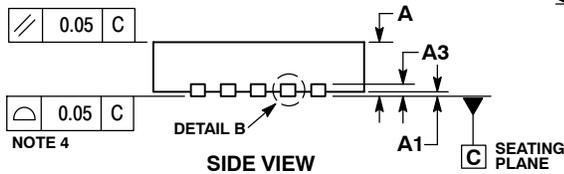
DATE 24 JUL 2012



NOTES:

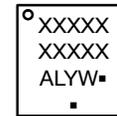
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	3.50 BSC	
D2	2.10	2.30
E	3.50 BSC	
E2	2.10	2.30
e	0.50 BSC	
K	0.30 REF	
L	0.25	0.45
L1	0.00	0.15



DETAIL B
ALTERNATE CONSTRUCTIONS

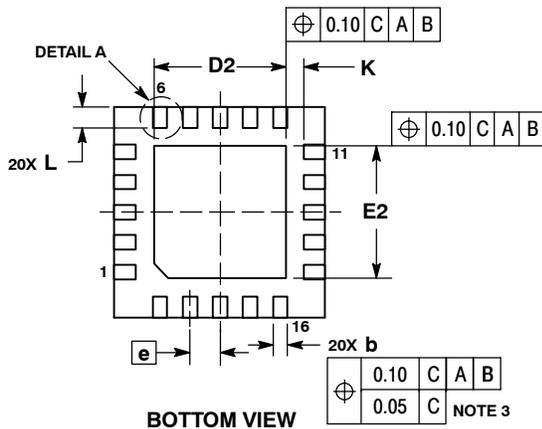
GENERIC MARKING DIAGRAM*



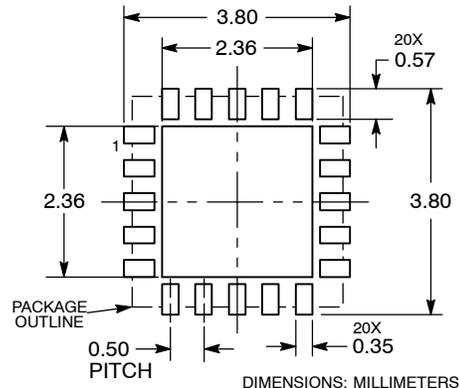
- XXXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present.



RECOMMENDED MOUNTING FOOTPRINT



DOCUMENT NUMBER:	98AON81889E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN20 3.5X3.5, 0.5P	
		PAGE 1 OF 2

